

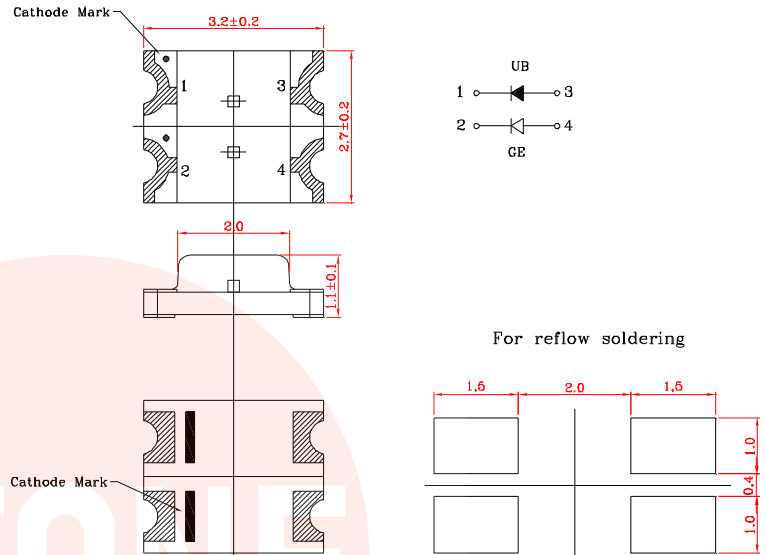
● Features:

1. Emitted Color : Super Red and Super Yellow Green.
2. Lens Appearance : Water Clear
3. Bi-color type.
4. 3.2x2.7x1.1mm(1210) standard package
5. Suitable for all SMT assembly methods.
6. Compatible with infrared and vapor phase reflow solder process.
7. Compatible with automatic placement equipment.
8. This product doesn't contain restriction Substance, comply ROHS standard.

● Applications:

1. Backlighting: LCDs, Key pads advertising.
2. Status indicators: Consumer & industrial electronics.
3. General use.

● Package Dimensions:



NOTES:

1. All dimensions are in millimeters .
2. Tolerance is $\pm 0.10\text{mm}$ unless otherwise specified.
3. Specifications are subject to change without notice.

● Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

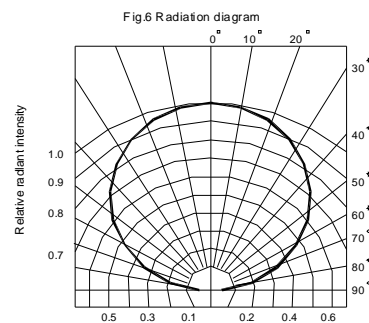
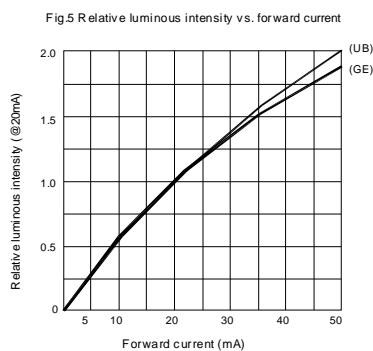
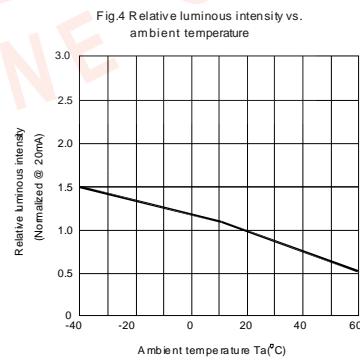
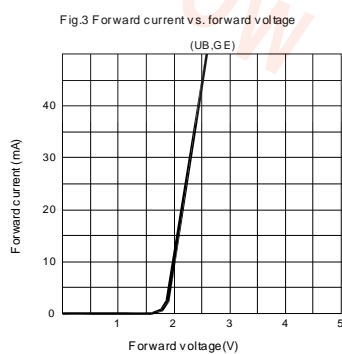
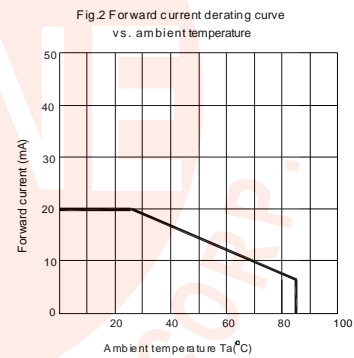
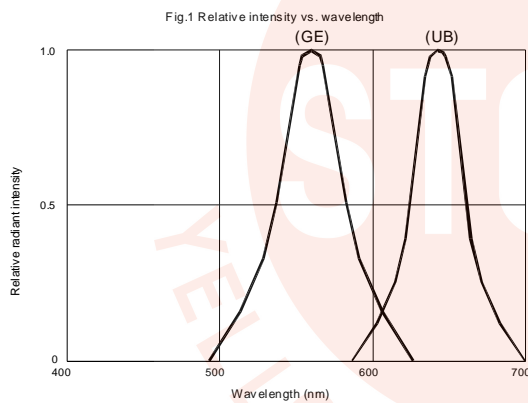
| Parameter | Symbol | Super Red | Super Yellow Green | Unit |
|--------------------------|-----------|---|--------------------|------|
| Power Dissipation | P_d | 50 | 50 | mW |
| Forward Current | I_F | 20 | 20 | mA |
| Peak Forward Current * 1 | I_{FP} | 100 | 100 | mA |
| Reverse Voltage | V_R | 5 | | V |
| Operating Temperature | T_{opr} | $-40^\circ\text{C} \sim 85^\circ\text{C}$ | | - |
| Storage Temperature | T_{stg} | $-40^\circ\text{C} \sim 85^\circ\text{C}$ | | - |
| Soldering Temperature | T_{sol} | See Page 6 | | - |

* 1 Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

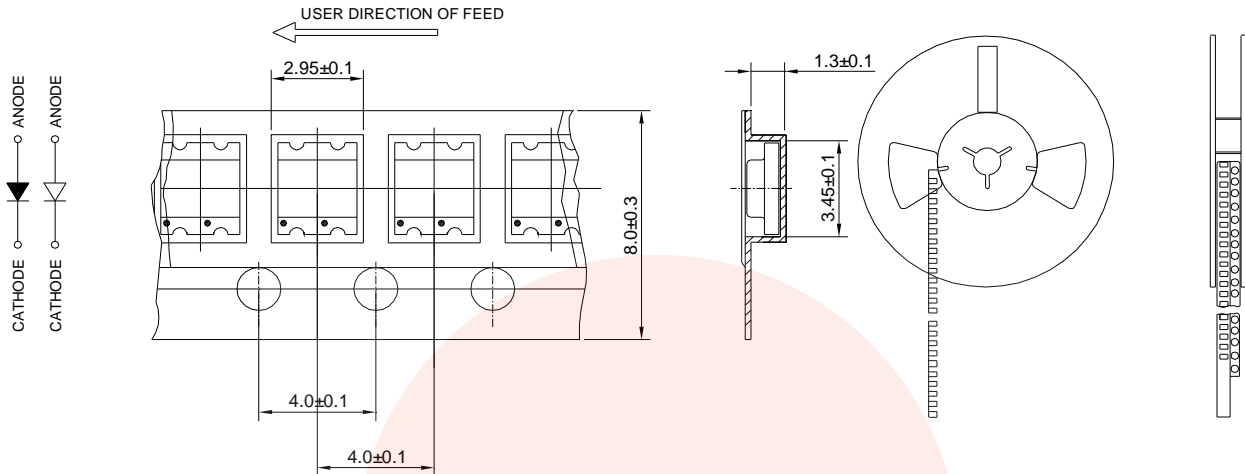
| Parameter | Symbol | Condition | Color | Min. | Typ. | Max. | Unit |
|----------------------|-------------------|----------------------|---------------------------------|------------|------------|------------|------|
| Forward Voltage | V _f | I _F =20mA | Super Red Super Yellow Green | - | 2.2 2.2 | 2.6 2.6 | V |
| Luminous Intensity | I _v | I _F =20mA | Super Red Super Yellow Green | 28 18.5 | 50 35 | - | mcd |
| Reverse Current | I _R | V _R =5V | Super Red Super Yellow Green | - | - | 100 | μA |
| Peak Wave Length | λ _p | I _F =20mA | Super Red Super Yellow Green | - | 645 570 | - | nm |
| Dominant Wave Length | λ _d | I _F =20mA | Super Red Super Yellow Green | 625 566 | - | 640 576 | nm |
| Viewing Angle | 2θ _{1/2} | I _F =20mA | Super Red Super Yellow Green | - | 120 | - | deg |

● Typical Electro-Optical Characteristics Curves

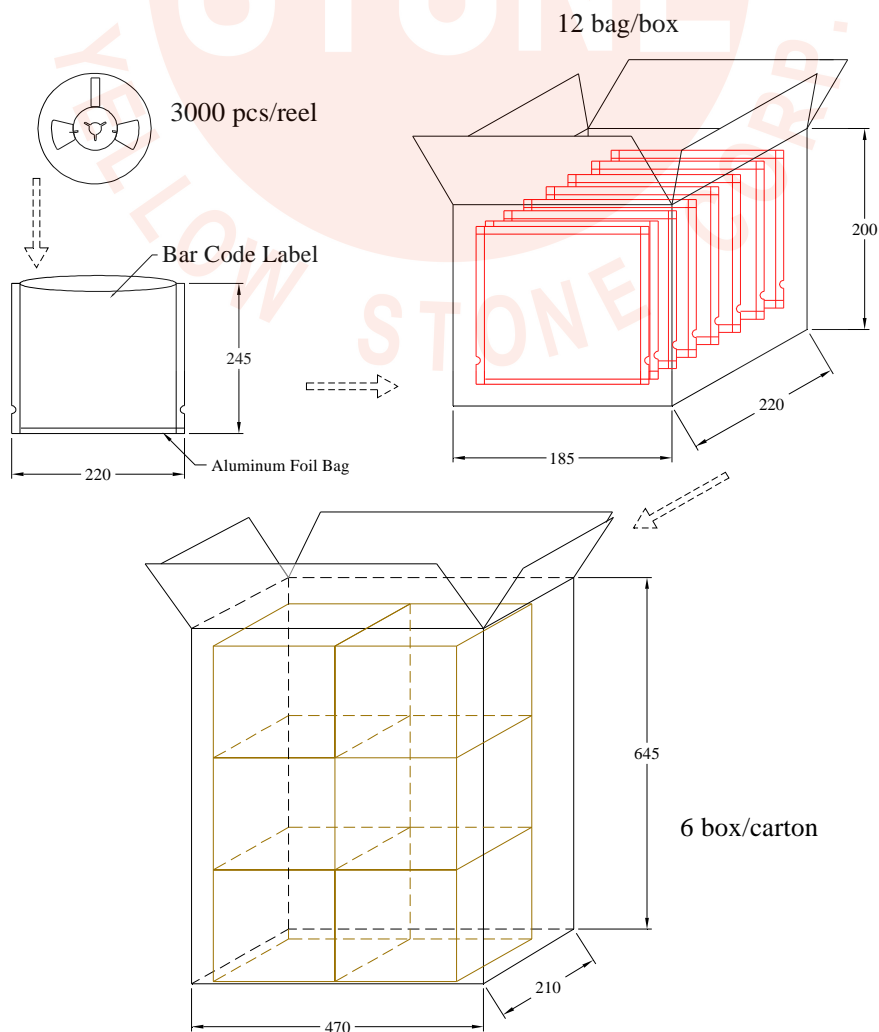


● Tapping and packaging specifications(Units: mm)

Quantity:3000PCS



● Package Method:(unit: mm)Vacuum





● Bin Limits:

Intensity Bin Limits (UB) (At 20mA)

| BIN CODE | Min. (mcd) | Max. (mcd) |
|----------|------------|------------|
| M | 28 | 42 |
| N | 42 | 63 |
| P | 63 | 94 |
| Q | 94 | 140 |

Tolerance for each Bin limit is $\pm 15\%$

Intensity Bin Limits (GE) (At 20mA)

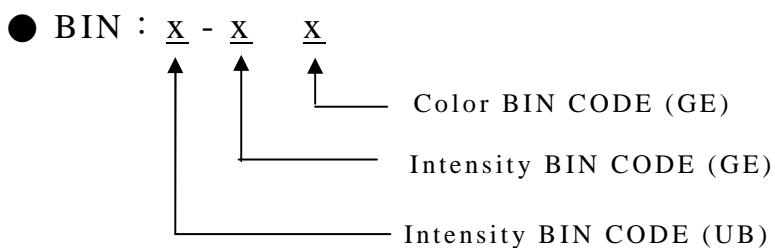
| BIN CODE | Min. (mcd) | Max. (mcd) |
|----------|------------|------------|
| L | 18.5 | 28 |
| M | 28 | 42 |
| N | 42 | 63 |
| P | 63 | 94 |

Tolerance for each Bin limit is $\pm 15\%$

Color Bin Limits (GE) (At 20mA)

| BIN CODE | Min. (nm) | Max. (nm) |
|----------|-----------|-----------|
| 4a | 566 | 567 |
| 4b | 567 | 568 |
| 5a | 568 | 569 |
| 5b | 569 | 570 |
| 6a | 570 | 571 |
| 6b | 571 | 572 |
| 7a | 572 | 573 |
| 7b | 573 | 574 |
| 8a | 574 | 575 |
| 8b | 575 | 576 |

Tolerance for each Bin limit is $\pm 1\text{nm}$.





● Reliability Test

| Classification | Test Item | Reference Standard | Test Conditions | Result |
|--------------------|--|--|---|--------|
| Endurance Test | Operation Life | MIL-STD-750D:1026 MIL-STD-883D:1005 JIS-C-7021 :B-1 | Ta: Under room temperature Test time:1,000hrs IF=Product Recommended IF | 0/32 |
| | High Temperature High Humidity Storage | MIL-STD-202F:103B JIS-C-7021 :B-11 | Ta:85±5℃ RH:90%-95% Test time:240hrs | 0/32 |
| | High Temperature Storage | MIL-STD-883:1008 JIS-C-7021 :B-10 | Ta:100±5℃ Test time:1,000hrs | 0/32 |
| | Low Temperature Storage | JIS-C-7021 :B-11 | Ta: -40±5℃ Test time=1,000hrs | 0/32 |
| Environmental Test | Temperature Cycling | MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS-C-7021 :A-2 | Ta:-35±5℃~25±5℃~85±5℃~25±5℃ 30min 5min 30min 5min Time: 5cycles | 0/32 |
| | Thermal Shock | MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011(1991) | Ta:-40±5℃ ~+85±5℃ 20min 20 min Time: 10cycles | 0/32 |
| | Wetting balance | MIL-STD-883:2003 MIL-STD-202F:208D MIL-STD-883D:2003 | Ta:230±5℃ Time:5±0.5s | 0/32 |
| | Solder Resistance | MIL-STD-202F:210A MIL-STD-883D:1011 JIS-C-7021 :A-1 | Ta:260±10℃ Time:10±1s | 0/32 |

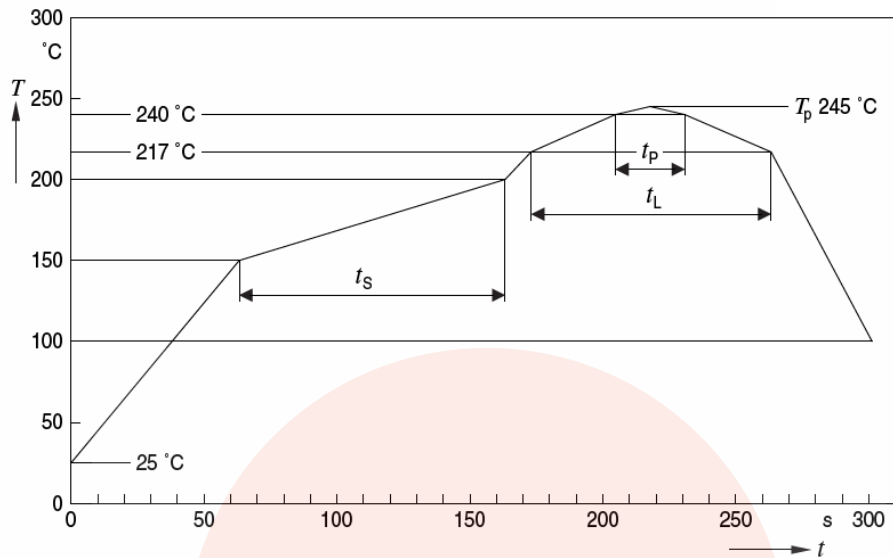
● Judgment criteria of failure for the reliability

| Measuring items | Symbol | Measuring conditions | Judgement criteria for failure |
|--------------------|--------------------|----------------------|--------------------------------|
| Forward voltage | V_F (V) | $I_F=20\text{mA}$ | Initial Level*1.1 |
| Reverse current | $I_R(\mu\text{A})$ | $V_R=5\text{V}$ | Over U*2 |
| Luminous intensity | I_v (mcd) | $I_F=20\text{mA}$ | Initial Level*0.7 |

Note: 1.U means the upper limit of specified characteristics.

2. Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

● IR-Reflow Soldering



| Profile Feature | Symbol | Pb-Free (SnAgCu) Assembly | | | Unit |
|--|--------|---------------------------|----------------|---------|--------------------|
| | | Minimum | Recommendation | Maximum | |
| Ramp-up rate to preheat ¹⁾ 25 $^{\circ}\text{C}$ to 150 $^{\circ}\text{C}$ | | | 2 | 3 | K/s |
| Time t_s T_{smin} to T_{smax} | t_s | 60 | 100 | 120 | s |
| Ramp-up rate to peak ²⁾ T_{smax} to T_p | | | 2 | 3 | K/s |
| Liquidus temperature | T_L | | 217 | | $^{\circ}\text{C}$ |
| Time above liquidus temperature | t_L | | 80 | 100 | s |
| Peak temperature | T_p | | 245 | 260 | $^{\circ}\text{C}$ |
| Time within 5 $^{\circ}\text{C}$ of the specified peak temperature $T_p - 5\text{ K}$ | t_p | 10 | 20 | 30 | s |
| Ramp-down rate* T_p to 100 $^{\circ}\text{C}$ | | | 3 | 6 | K/s |
| Time 25 $^{\circ}\text{C}$ to T_p | | | | 480 | s |

All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

1. Avoid any external stress applied to the resin while the LEDs are at high temperature, especially during soldering.
2. Avoid rapid cooling or any excess vibration during temperature ramp-down process.
3. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs.

● IRON Soldering

350 $^{\circ}\text{C}$ Within 3 sec.,One time only.

● **Notes for designing:**

Care must be taken to provide the current limiting resistor in the circuit so as to drive the BRIGHT LEDs within the rated figures. Also, caution should be taken not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as to be subjected to reverse voltage when turning off the BRIGHT LEDs.

● **Storage:**

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F) Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
48 hours at 60°C±3°C.

● **Package and Label of Products:**

- (1) Package: Products are packed in one bag of 3000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

